EloPin® PRESS-FIT by LEMAN industrie

PRESS-FIT SOLUTION

ABOUT TBS Sorig

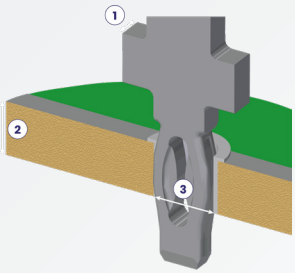
- In partnership with LEMAN industrie
- License owner of EloPin
- A product developer
- Based in Germany
- Over 20 years experience

BENEFITS OF THE EloPin® PRESS-FIT

- Low press-in force & high push-out force
- No tin chips
- High mechanical stability
- Gas-tight, reliable connection
- Low mechanical stress on the PCB during press-in process
- No «nozzle effect» (deformation of the PCB layers from press-in)
- Temperature range from -40°C to 150°C (rem. 1)
- Low electric resistance

EloPin® SIZES / VARIANTS

Name	Material Thickness	PTH Diameter	PCB Thickness
EloPin 04-06	0,4 mm	0,6 mm	1,0 mm
EloPin 06-10	0,6 mm	1,0 mm	1,44 (1,0) mm
EloPin 08-145	0,8 mm	1,45 mm	1,44 mm
EloPin 08-16	0,8 mm	1,6 mm	1,44 mm
EloPin 12-20	1,2 mm	2,0 mm	1,44 mm



1. Material Thickness
2. PCB Thickness
3. PTH Diameter

TECHNICAL DATA

EloPin	04-06	06-10	08-145	08-16	12-20
Press-in Force, Max	100 N	100 N	160 N	160 N	200 N
Press-in Force, Typical	20-60 N	65 N	115 N	85 N	160 N
Push-out Force, Min	20 N	30 N	40 N	50 N	50 N
Push-out Force, Typical	35-70 N	60 N	135 N	105 N	110 N
Volume Resistance, Max	1 mOhm	1 mOhm	1 mOhm	1 mOhm	1 mOhm
Volume Resistance, Typical	0.05 mOhm	0.01 mOhm	0.01 mOhm	0.01 mOhm	0.01 mOhm
Current Capacity	Not tested	Approx. 8A	Approx. 25A	Approx. 25A	Approx. 45A

BASE MATERIALS

Application	Mobility	Mobility	Mobility
Base Material	CuSn6	CuNi3SiMg	CuCrAgFeTiSi
Electrical Conductivity MS/m	9	25	46
Thermal Con. W/(m.k)	75	190	320
Surface Finish	Sn100 on Ni	Sn100 on Ni	Sn100 on Ni
Max. Usage Temperature	95 °C	150 °C	150 °C
EloPin 04-06	✓	✓	
EloPin 06-10	✓	✓	
EloPin 08-145		✓	✓
EloPin 08-16	✓	✓	
EloPin 12-20		✓	✓

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